

Dr. An-Yu Kuo, Optimal Corporation CTO, to Participate in Thermal Performance Panel at DesignCon 2007

WHAT: Optimal Corporation, a leading supplier of 3D electrical and thermal analysis tools will help raise awareness of effective strategies for thermal performance with its participation in the following panel at DesignCon 2007:

Keeping It Cool: Strategies and Considerations for Dealing with Thermal Performance

Moderator: Margery Conner, EDN Technical Editor

Panelists:

- Andrew T. Yang, Apache Design Solutions
- Javier DeLaCruz, eSilicon Corporation
- Prabhu Sathyamurthy, Fluent Incorporated
- An-Yu Kuo, Optimal Corporation

For more information on the panel and its participants, please go to http://www.designcon.com/2007/conference/bfp1_tuesday.html

WHEN: Tuesday, January 30, 2007, at 8.30am

WHERE: DesignCon 2007
Santa Clara Convention Center, Santa Clara, Calif.
January 29 – February 1, 2007

WHO: Optimal Corporation, founded in 1995, is a leader in 3D Power, Signal and Thermal Integrity analysis for IC Package, System-in-Package (SiP) and PCB design. Our innovative solutions enable design teams to concurrently analyze and optimize the IC together with the Package and the Packaged IC on the PCB. Through seamless integration with all of the major CAD design flows, Optimal solutions help customers achieve the shortest and most efficient overall design cycle time. Optimal's technology is embedded in the Cadence Allegro flow and endorsed in the TSMC Reference Flow. Optimal is a TSMC Technology Alliance Partner and a member of the Cadence Connections Emerging Solutions Program.

Optimal has over 50 customers around the globe, including many of the world's leading semiconductor, IC packaging and systems companies. For more information visit www.optimalcorp.com

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